1 Megabit (128K x8) Page-Mode EEPROM
SST29EE010A / SST29LE010A / SST29VE010A

Data Sheet

FEATURES:

- **Single Voltage Read and Write Operations**
  - 5.0V-only for the SST29EE010A
  - 3.0-3.6V for the SST29LE010A
  - 2.7-3.6V for the SST29VE010A
- **Superior Reliability**
  - Endurance: 100,000 Cycles (typical)
  - Greater than 100 years Data Retention
- **Low Power Consumption**
  - Active Current: 20 mA (typical) for 5V and 10 mA (typical) for 3.0/2.7V
  - Standby Current: 10 µA (typical)
- **Fast Page-Write Operation**
  - 128 Bytes per Page, 1024 Pages
  - Page-Write Cycle: 5 ms (typical)
  - Complete Memory Rewrite: 5 sec (typical)
  - Effective Byte-Write Cycle Time: 39 µs (typical)
- **Fast Read Access Time**
  - 5.0V-only operation: 90 and 120 ns
  - 3.0-3.6V operation: 150 and 200 ns
  - 2.7-3.6V operation: 200 and 250 ns
- **Latched Address and Data**
- **Automatic Write Timing**
  - Internal V_{PP} Generation
- **End-of-Write Detection**
  - Toggle Bit
  - Data# Polling
- **Hardware and Software Data Protection**
- **TTL I/O Compatibility**
- **JEDEC Standard**
  - Flash EEPROM Pinouts and command sets
- **Packages Available**
  - 32 Pin PDIP
  - 32-Pin PLCC
  - 32-Pin TSOP (8mm x 14mm & 8mm x 20mm)

PRODUCT DESCRIPTION

The SST29EE010A/29LE010A/29VE010A are 128K x8 CMOS Page-Write EEPROMs manufactured with SST's proprietary, high performance CMOS SuperFlash technology. The split-gate cell design and thick oxide tunneling injector attain better reliability and manufacturability compared with alternate approaches. The SST29EE010A/29LE010A/29VE010A write with a single power supply. Internal Erase/Program is transparent to the user. The SST29EE010A/29LE010A/29VE010A conform to JEDEC standard pinouts for byte-wide memories.

Featuring high performance Page-Write, the SST29EE010A/29LE010A/29VE010A provide a typical Byte-Write time of 39 µsec. The entire memory, i.e., 128 KBytes, can be written page-by-page in as little as 5 seconds, when using interface features such as Toggle Bit or Data# Polling to indicate the completion of a Write cycle. To protect against inadvertent write, the SST29EE010A/29LE010A/29VE010A have on-chip hardware and Software Data Protection schemes. Designed, manufactured, and tested for a wide spectrum of applications, the SST29EE010A/29LE010A/29VE010A are offered with a guaranteed Page-Write endurance of 10^4 cycles. Data retention is rated at greater than 100 years.

The SST29EE010A/29LE010A/29VE010A are suited for applications that require convenient and economical updating of program, configuration, or data memory. For all system applications, the SST29EE010A/29LE010A/29VE010A significantly improve performance and reliability, while lowering power consumption. The SST29EE010A/29LE010A/29VE010A improve flexibility while lowering the cost for program, data, and configuration storage applications.

To meet high density, surface mount requirements, the SST29EE010A/29LE010A/29VE010A are offered in 32-pin TSOP and 32-lead PLCC packages. A 600-mil, 32-pin PDIP package is also available. See Figures 1 and 2 for pinouts.

Device Operation

The SST Page-Mode EEPROM offers in-circuit electrical write capability. The SST29EE010A/29LE010A/29VE010A does not require separate Erase and Program operations. The internally timed write cycle executes both erase and program transparently to the user. The SST29EE010A/29LE010A/29VE010A have industry standard Software Data Protection. The SST29EE010A/29LE010A/29VE010A are compatible with industry standard EEPROM pinouts and functionality.

Read

The Read operations of the SST29EE010A/29LE010A/29VE010A are controlled by CE# and OE#, both have to be low for the system to obtain data from the outputs.

CE# is used for device selection. When CE# is high, the chip is deselected and only standby power is consumed. OE# is the output control and is used to gate data from the output pins. The data bus is in high impedance state when either CE# or OE# is high. Refer to the read cycle timing diagram for further details (Figure 3).

Write

The Page-Write to the SST29EE010A/29LE010A/29VE010A uses the JEDEC Standard Software Data Protection (SDP) three-byte command sequence.

The Write operation consists of three steps. Step 1 is the three-byte load sequence for Software Data Protection. Step 2 is the byte-load cycle to a page buffer of the SST29EE010A/29LE010A/29VE010A. Steps 1 and 2 use the same timing for both operations. Step 3 is an internally controlled write cycle for writing the data loaded in the page buffer into the memory array for nonvolatile storage. During both the SDP three-byte load sequence and the byte-load cycle, the addresses are latched by the falling edge of either CE# or WE#, whichever occurs last. The data is latched by the rising edge of either CE# or WE#, whichever occurs first. The internal write cycle is initiated by the T_{BLCO} timer after the rising edge of WE# or CE#, whichever occurs first. The Write cycle, once initiated, will continue to completion, typically within 5 ms. See Figures 4 and 5 for WE# and CE# controlled Page-Write cycle timing diagrams and Figures 13 and 15 for flowcharts.

The Write operation has three functional cycles: the Software Data Protection load sequence, the page load cycle, and the internal write cycle. The Software Data Protection consists of a specific three-byte load sequence that allows writing to the selected page and will leave the SST29EE010A/29LE010A/29VE010A protected at the end of the Page-Write. The page load cycle consists of loading 1 to 128 Bytes of data into the page buffer. The internal write cycle consists of the T_{BLCO} time-out and the write timer operation. During the Write operation, the only valid reads are Data# Polling and Toggle Bit.

The Page-Write operation allows the loading of up to 128 Bytes of data into the page buffer of the SST29EE010A/29LE010A/29VE010A before the initiation of the internal write cycle. During the internal write cycle, all the data in the page buffer is written simultaneously into the memory array. Hence, the Page-Write feature of SST29EE010A/29LE010A/29VE010A allow the entire memory to be written in as little as 5 seconds. During the internal write cycle, the host is free to perform additional tasks, such as to fetch data from other locations in the system to set up the write to the next page. In each Page-Write operation, all the bytes that are loaded into the page buffer must have the same page address, i.e. A_7 through A_{16}. Any byte not loaded with user data will be written to FF.

See Figures 4 and 5 for the Page-Write cycle timing diagrams. If after the completion of the three-byte SDP load sequence the host loads a byte into the page buffer within a byte-load cycle time (T_{BLC}) of 100 µs, the SST29EE010A/29LE010A/29VE010A will stay in the page load cycle. Additional bytes are then loaded consecutively. The page load cycle will be terminated if no additional byte is loaded into the page buffer within 200 µs (T_{BLCO}) from the last byte-load cycle, i.e., no subsequent WE# or CE# high-to-low transition after the last rising edge of WE# or CE#. Data in the page buffer can be changed by a subsequent byte-load cycle. The page load period can continue indefinitely, as long as the host continues to load the device within the byte-load cycle time of 100 µs. The page to be loaded is determined by the page address of the last byte loaded.

Software Chip-Erase

The SST29EE010A/29LE010A/29VE010A provide a Chip-Erase operation, which allows the user to simultaneously clear the entire memory array to the “1” state. This is useful when the entire device must be quickly erased.

The Software Chip-Erase operation is initiated by using a specific six-byte load sequence. After the load sequence, the device enters into an internally timed cycle similar to the Write cycle. During the Erase operation, the only valid read is Toggle Bit. See Table 4 for the load sequence, Figure 8 for timing diagram, and Figure 17 for the flowchart.

Write Operation Status Detection

The SST29EE010A/29LE010A/29VE010A provide two software means to detect the completion of a Write cycle, in order to optimize the system write cycle time. The software detection includes two status bits: Data# Polling (DQ_7) and Toggle Bit (DQ_6). The End-of-Write detection mode is enabled after the rising WE# or CE# whichever occurs first, which initiates the internal write cycle.

The actual completion of the nonvolatile write is asynchronous with the system; therefore, either a Data# Polling or Toggle Bit read may be simultaneous with the completion of the Write cycle. If this occurs, the system may possibly get an erroneous result, i.e., valid data may appear to conflict with either DQ_7 or DQ_6. In order to prevent spurious rejection, if an erroneous result occurs, the software routine should include a loop to read the accessed location an additional two (2) times. If both reads are valid, then the device has completed the Write cycle, otherwise the rejection is valid.

Data# Polling (DQ_7)

When the SST29EE010A/29LE010A/29VE010A are in the internal write cycle, any attempt to read DQ_7 of the last byte loaded during the byte-load cycle will receive the complement of the true data. Once the Write cycle is completed, DQ_7 will show true data. The device is then ready for the next operation. See Figure 6 for Data# Polling timing diagram and Figure 14 for a flowchart.

Toggle Bit (DQ_6)

During the internal write cycle, any consecutive attempts to read DQ_6 will produce alternating 0's and 1's, i.e. toggling between 0 and 1. When the Write cycle is completed, the toggling will stop. The device is then ready for the next operation. See Figure 7 for Toggle Bit timing diagram and Figure 14 for a flowchart. The initial read of the Toggle Bit will typically be a "1".

Data Protection

The SST29EE010A/29LE010A/29VE010A provide both hardware and software features to protect nonvolatile data from inadvertent writes.

Hardware Data Protection

Noise/Glitch Protection: A WE# or CE# pulse of less than 5 ns will not initiate a Write cycle.

V_{CC} Power Up/Down Detection: The Write operation is inhibited when V_{CC} is less than 2.5V.

Write Inhibit Mode: Forcing OE# low, CE# high, or WE# high will inhibit the Write operation. This prevents inadvertent writes during power-up or power-down.

Software Data Protection (SDP)

The SST29EE010A/29LE010A/29VE010A provide the JEDEC approved Software Data Protection scheme for all data alteration operations, i.e., Write and Chip-Erase. With this scheme, any Write operation requires the inclusion of a series of three byte-load operations to precede the data loading operation. The three byte-load sequence is used to initiate the Write cycle, providing optimal protection from inadvertent write operations, e.g., during the system power-up or power-down.

Product Identification

The product identification mode identifies the device as the SST29EE010A/29LE010A/29VE010A and manufacturer as SST. This mode may be accessed by hardware or software operations. The hardware operation is typically used by a programmer to identify the correct algorithm for the SST29EE010A/29LE010A/29VE010A. Users may wish to use the software product identification operation to identify the part (i.e. using the device code) when using multiple manufacturers in the same socket. For details, see Table 3 for hardware operation or Table 4 for software operation, Figure 9 for the software ID entry and read timing diagram and Figure 16 for the ID entry command sequence flowchart. The manufacturer and device codes are the same for both operations.

Product Identification Mode Exit

In order to return to the standard read mode, the Software Product Identification mode must be exited. Exiting is accomplished by issuing the Software ID Exit (reset) operation, which returns the device to the Read operation. The Reset operation may also be used to reset the device to the read mode after an inadvertent transient condition that apparently causes the device to behave abnormally, e.g. not read correctly. See Table 4 for software command codes, Figure 10 for timing waveform and Figure 16 for a flowchart.

TABLE 1: PRODUCT IDENTIFICATION TABLE

	Byte	Data
Manufacturer's Code	0000 H	BF H
SST29EE010A Device Code	0001 H	22 H
SST29LE010A Device Code	0001 H	23 H
SST29VE010A Device Code	0001 H	23 H

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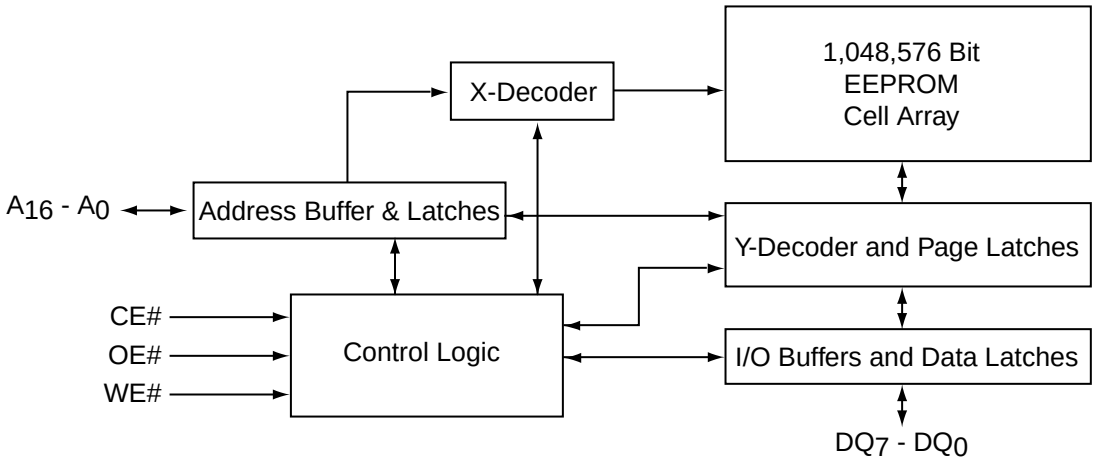
FUNCTIONAL BLOCK DIAGRAM OF SST 29EE010A/29LE010A/29VE010A



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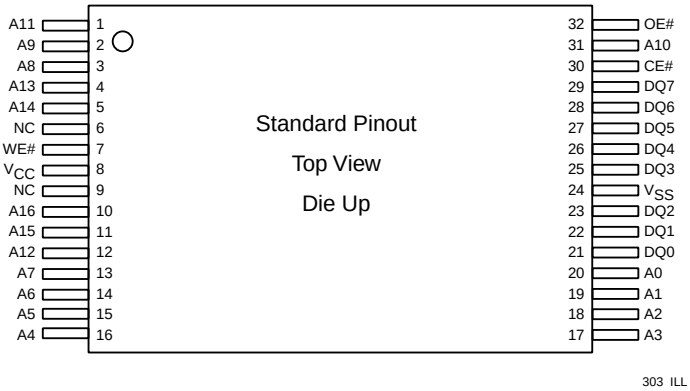

FIGURE 1: PIN ASSIGNMENTS FOR 32-PIN TSOP PACKAGES

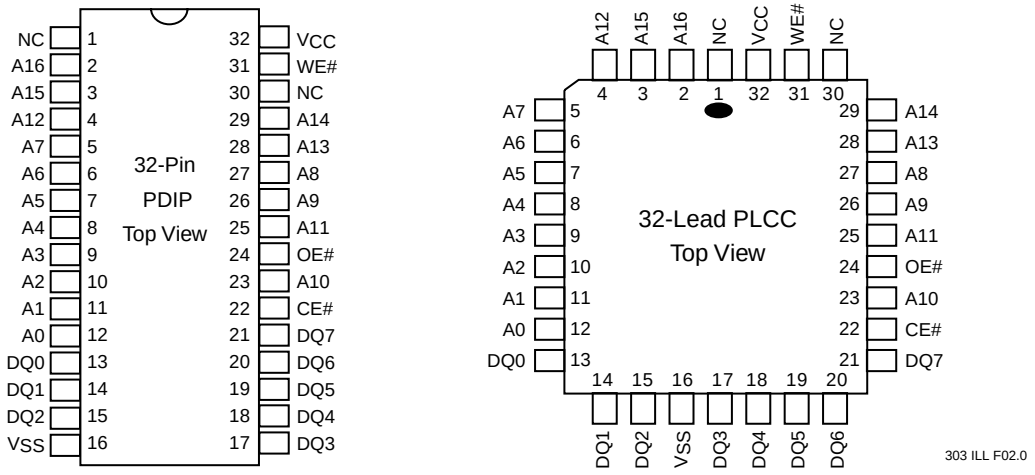

FIGURE 2: PIN ASSIGNMENTS FOR 32-PIN PLASTIC DIPS AND 32-LEAD PLCCS

TABLE 2: PIN DESCRIPTION

Symbol	Pin Name	Functions
A_{16}-A_7	Row Address Inputs	To provide memory addresses. Row addresses define a page for a Write cycle.
A_6-A_0	Column Address Inputs	Column Addresses are toggled to load page data.
DQ_7-DQ_0	Data Input/output	To output data during Read cycles and receive input data during Write cycles. Data is internally latched during a Write cycle. The outputs are in tri-state when OE# or CE# is high.
CE#	Chip Enable	To activate the device when CE# is low.
OE#	Output Enable	To gate the data output buffers.
WE#	Write Enable	To control the Write operations
Vcc	Power Supply	To provide 5-volt supply (± 10%) for the SST29EE010A, 3-volt supply (3.0-3.6V) for the SST29LE010A and 2.7-volt supply (2.7-3.6V) for the SST29VE010A
Vss	Ground	
NC	No Connection	Unconnected pins.

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TABLE 3: OPERATION MODES SELECTION

Mode	CE#	OE#	WE#	DQ	Address
Read	V_{IL}	V_{IL}	V_{IH}	D_{OUT}	A_{IN}
Page-Write	V_{IL}	V_{IH}	V_{IL}	D_{IN}	A_{IN}, See Table 4
Standby	V_{IH}	X	X	High Z	X
Write Inhibit	X	V_{IL}	X	High Z/ D_{OUT}	X
Write Inhibit	X	X	V_{IH}	High Z/ D_{OUT}	X
Software Chip-Erase	V_{IL}	V_{IH}	V_{IL}	D_{IN}	A_{IN}, See Table 4
Product Identification					
Hardware Mode	V_{IL}	V_{IL}	V_{IH}	Manufacturer Code (BF)	A_{16} - A_1 = V_{IL}, A_9 = V_H, A_0 = V_{IL}
				Device Code (see notes)	A_{16} - A_1 = V_{IL}, A_9 = V_H, A_0= V_{IH}
Software Mode	V_{IL}	V_{IH}	V_{IL}		See Table 4
SDP Enable Mode	V_{IL}	V_{IH}	V_{IL}		See Table 4

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TABLE 4: SOFTWARE COMMAND CODES

Command Sequence	1st Bus Write Cycle		2nd Bus Write Cycle		3rd Bus Write Cycle		4th Bus Write Cycle		5th Bus Write Cycle		6th Bus Write Cycle	
	Addr(1)	Data	Addr(1)	Data	Addr(1)	Data	Addr(1)	Data	Addr(1)	Data	Addr(1)	Data
Page-Write	5555H	AAH	2AAAH	55H	5555H	A0H	Addr(2)	Data				
Software Chip-Erase	5555H	AAH	2AAAH	55H	5555H	80H	5555H	AAH	2AAAH	55H	5555H	10H
Software ID Entry	5555H	AAH	2AAAH	55H	5555H	90H						
Software ID Exit	5555H	AAH	2AAAH	55H	5555H	F0H						
Alternate Software ID Entry(3)	5555H	AAH	2AAAH	55H	5555H	80H	5555H	AAH	2AAAH	55H	5555H	60H

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Notes: (1) Address format A_{14}-A_0 (Hex), Addresses A_{15} and A_{16} are a "Don't Care".
(2) Page-Write consists of loading up to 128 Bytes (A_6 - A_0).
(3) Alternate six-byte software Product-ID Command Code
(4) The software Chip-Erase function is not supported by the industrial temperature part.
Please contact SST, if you require this function for an industrial temperature part.

Notes for Software Product ID Command Code:

1. With A_{14} -A_1 =0; SST Manufacturer Code = BFH, is read with A_0 = 0,
SST29EE010A Device Code = 22H, is read with A_0 = 1.
SST29LE010A/29VE010A Device Code = 23H, is read with A_0 = 1.
2. The device does not remain in Software Product ID Mode if powered down.
3. This device supports both the JEDEC standard three-byte command code sequence and SST's original six-byte command code sequence. For new designs, SST recommends the three-byte command code sequence be used.

Absolute Maximum Stress Ratings (Applied conditions greater than those listed under "Absolute Maximum Stress Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the operational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.)

Temperature Under Bias ..... -55°C to +125°C
Storage Temperature ..... -65°C to +150°C
D. C. Voltage on Any Pin to Ground Potential ..... -0.5V to V_{CC}+ 0.5V
Transient Voltage (<20 ns) on Any Pin to Ground Potential ..... -1.0V to V_{CC}+ 1.0V
Voltage on A_9 Pin to Ground Potential ..... -0.5V to 14.0V
Package Power Dissipation Capability (Ta = 25°C) 1.0W
Through Hole Lead Soldering Temperature (10 Seconds) ..... 300°C
Surface Mount Lead Soldering Temperature (3 Seconds) ..... 240°C
Output Short Circuit Current[1] ..... 100 mA

Note: [1] Outputs shorted for no more than one second. No more than one output shorted at a time.

SST29EE010A OPERATING RANGE

Range	Ambient Temp	V_{CC}
Commercial	0°C to +70°C	5V±10%
Industrial	-40°C to +85°C	5V±10%

SST29LE010A OPERATING RANGE

Range	Ambient Temp	V_{CC}
Commercial	0°C to +70°C	3.0V to 3.6V
Industrial	-40°C to +85°C	3.0V to 3.6V

SST29VE010A OPERATING RANGE

Range	Ambient Temp	V_{CC}
Commercial	0°C to +70°C	2.7V to 3.6V
Industrial	-40°C to +85°C	2.7V to 3.6V

AC CONDITIONS OF TEST

Input Rise/Fall Time ..... 10 ns
Output Load ..... 1 TTL Gate and C_L = 100 pF
See Figures 12 and 13

TABLE 5: SST29EE010A DC OPERATING CHARACTERISTICS V_{CC} = 5V±10%

Symbol	Parameter	Limits			Test Conditions
		Min	Max	Units	
I_{CC}	Power Supply Current				CE#=OE#=V_{IL},WE#=V_{IH} , all I/Os open,
	Read		30	mA	Address input = V_{IL}/V_{IH}, at f=1/T_{RC} Min., V_{CC}=V_{CC} Max
	Write		50	mA	CE#=WE#=V_{IL}, OE#=V_{IH}, V_{CC} =V_{CC} Max.
I_{SB1}	Standby V_{CC} Current (TTL input)		3	mA	CE#=OE#=WE#=V_{IH}, V_{CC} =V_{CC} Max.
I_{SB2}	Standby V_{CC} Current (CMOS input)		50	µA	CE#=OE#=WE#=V_{CC} -0.3V. V_{CC} = V_{CC} Max.
I_{LI}	Input Leakage Current		1	µA	V_{IN} =GND to V_{CC}, V_{CC} = V_{CC} Max.
I_{LO}	Output Leakage Current		10	µA	V_{OUT} =GND to V_{CC}, V_{CC} = V_{CC} Max.
V_{IL}	Input Low Voltage		0.8	V	V_{CC} = V_{CC} Min.
V_{IH}	Input High Voltage	2.0		V	V_{CC} = V_{CC} Max.
V_{OL}	Output Low Voltage		0.4	V	I_{OL} = 2.1 mA, V_{CC} = V_{CC} Min.
V_{OH}	Output High Voltage	2.4		V	I_{OH} = -400µA, V_{CC} = V_{CC} Min.
V_H	Supervoltage for A_9	11.6	12.4	V	CE# = OE# =V_{IL}, WE# = V_{IH}
I_H	Supervoltage Current for A_9		100	µA	CE# = OE# = V_{IL}, WE# = V_{IH}, A_9 = V_H Max.

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TABLE 6: SST29LE010A/29VE010A DC OPERATING CHARACTERISTICS V_{CC} = 3.0-3.6 FOR SST29LE010A, V_{CC} = 2.7-3.6 FOR SST29VE010A

Symbol	Parameter	Limits			Test Conditions
		Min	Max	Units	
I_{CC}	Power Supply Current				CE#=OE#=V_{IL},WE#=V_{IH} , all I/Os open,
	Read		12	mA	Address input = V_{IL}/V_{IH}, at f=1/T_{RC} Min., V_{CC}=V_{CC} Max
	Write		15	mA	CE#=WE#=V_{IL}, OE#=V_{IH}, V_{CC} =V_{CC} Max.
I_{SB1}	Standby V_{CC} Current (TTL input)		1	mA	CE#=OE#=WE#=V_{IH}, V_{CC} =V_{CC} Max.
I_{SB2}	Standby V_{CC} Current (CMOS input)		15	µA	CE#=OE#=WE#=V_{CC} -0.3V. V_{CC} = V_{CC} Max.
I_{LI}	Input Leakage Current		1	µA	V_{IN} =GND to V_{CC}, V_{CC} = V_{CC} Max.
I_{LO}	Output Leakage Current		10	µA	V_{OUT} =GND to V_{CC}, V_{CC} = V_{CC} Max.
V_{IL}	Input Low Voltage		0.8	V	V_{CC} = V_{CC} Min.
V_{IH}	Input High Voltage	2.0		V	V_{CC} = V_{CC} Max.
V_{OL}	Output Low Voltage		0.4	V	I_{OL} = 100 µA, V_{CC} = V_{CC} Min.
V_{OH}	Output High Voltage	2.4		V	I_{OH} = -100 µA, V_{CC} = V_{CC} Min.
V_H	Supervoltage for A_9	11.6	12.4	V	CE# = OE# =V_{IL}, WE# = V_{IH}
I_H	Supervoltage Current for A_9		100	µA	CE# = OE# = V_{IL}, WE# = V_{IH}, A_9 = V_H Max.

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TABLE 7: POWER-UP TIMINGS

Symbol	Parameter	Maximum	Units
$T_{PU-READ}$(1)	Power-up to Read Operation	100	µs
$T_{PU-WRITE}$(1)	Power-up to Write Operation	5	ms

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TABLE 8: CAPACITANCE (T_a = 25 °C, f=1 MHz, other pins open)

Parameter	Description	Test Condition	Maximum
$C_{I/O}$(1)	I/O Pin Capacitance	$V_{I/O}$ = 0V	12 pF
C_{IN}(1)	Input Capacitance	V_{IN} = 0V	6 pF

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Note: (1)This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

TABLE 9: RELIABILITY CHARACTERISTICS

Symbol	Parameter	Minimum Specification	Units	Test Method
N_{END}	Endurance	10,000	Cycles	JEDEC Standard A117
T_{DR}(1)	Data Retention	100	Years	JEDEC Standard A103
V_{ZAP_HBM}(1)	ESD Susceptibility Human Body Model	2000	Volts	JEDEC Standard A114
V_{ZAP_MM}(1)	ESD Susceptibility Machine Model	200	Volts	JEDEC Standard A115
I_{LTH}(1)	Latch Up	100	mA	JEDEC Standard 78

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Note: (1)This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

AC CHARACTERISTICS

TABLE 10: SST29EE010A READ CYCLE TIMING PARAMETERS

Symbol	Parameter	SST29EE010A-90		SST29EE010A-120		Units
		Min	Max	Min	Max	
T_{RC}	Read Cycle Time	90		120		ns
T_{CE}	Chip Enable Access Time		90		120	ns
T_{AA}	Address Access Time		90		120	ns
T_{OE}	Output Enable Access Time		40		50	ns
$T_{CLZ}^{(1)}$	CE# Low to Active Output	0		0		ns
$T_{OLZ}^{(1)}$	OE# Low to Active Output	0		0		ns
$T_{CHZ}^{(1)}$	CE# High to High-Z Output		30		30	ns
$T_{OHZ}^{(1)}$	OE# High to High-Z Output		30		30	ns
$T_{OH}^{(1)}$	Output Hold from Address Change	0		0		ns

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TABLE 11: SST29LE010A READ CYCLE TIMING PARAMETERS

Symbol	Parameter	SST29LE010A-150		SST29LE010A-200		Units
		Min	Max	Min	Max	
T_{RC}	Read Cycle Time	150		200		ns
T_{CE}	Chip Enable Access Time		150		200	ns
T_{AA}	Address Access Time		150		200	ns
T_{OE}	Output Enable Access Time		60		100	ns
$T_{CLZ}^{(1)}$	CE# Low to Active Output	0		0		ns
$T_{OLZ}^{(1)}$	OE# Low to Active Output	0		0		ns
$T_{CHZ}^{(1)}$	CE# High to High-Z Output		30		50	ns
$T_{OHZ}^{(1)}$	OE# High to High-Z Output		30		50	ns
$T_{OH}^{(1)}$	Output Hold from Address Change	0		0		ns

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TABLE 12: SST29VE010A READ CYCLE TIMING PARAMETERS

Symbol	Parameter	SST29VE010A-200		SST29VE010A-250		Units
		Min	Max	Min	Max	
T_{RC}	Read Cycle Time	200		250		ns
T_{CE}	Chip Enable Access Time		200		250	ns
T_{AA}	Address Access Time		200		250	ns
T_{OE}	Output Enable Access Time		100		120	ns
$T_{CLZ}^{(1)}$	CE# Low to Active Output	0		0		ns
$T_{OLZ}^{(1)}$	OE# Low to Active Output	0		0		ns
$T_{CHZ}^{(1)}$	CE# High to High-Z Output		50		50	ns
$T_{OHZ}^{(1)}$	OE# High to High-Z Output		50		50	ns
$T_{OH}^{(1)}$	Output Hold from Address Change	0		0		ns

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TABLE 13: PAGE-WRITE CYCLE TIMING PARAMETERS

		SST29EE010A		SST29LE/VE010A		
Symbol	**Parameter**	**Min**	**Max**	**Min**	**Max**	**Units**
T_{WC}	Write Cycle (Erase and Program)		10		10	ms
T_{AS}	Address Setup Time	0		0		ns
T_{AH}	Address Hold Time	50		70		ns
T_{CS}	WE# and CE# Setup Time	0		0		ns
T_{CH}	WE# and CE# Hold Time	0		0		ns
T_{OES}	OE# High Setup Time	0		0		ns
T_{OEH}	OE# High Hold Time	0		0		ns
T_{CP}	CE# Pulse Width	70		120		ns
T_{WP}	WE# Pulse Width	70		120		ns
T_{DS}	Data Setup Time	35		50		ns
T_{DH}	Data Hold Time	0		0		ns
T_{BLC}(1)	Byte Load Cycle Time	0.05	100	0.05	100	µs
T_{BLCO}(1)	Byte Load Cycle Time	200		200		µs
T_{IDA}	Software ID Access and Exit Time		10		10	µs
T_{SCE}	Software Chip-Erase		20		20	ms

303 PGM T13.1

Note: (1)This parameter is measured only for initial qualification and after the design or process change that could affect this parameter.

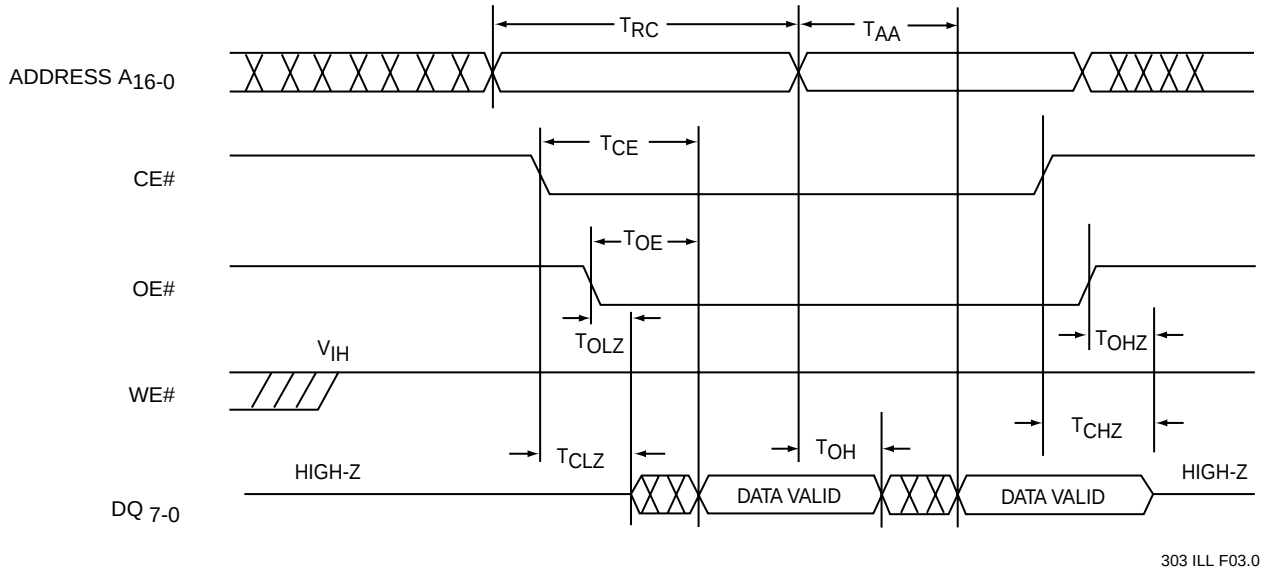


FIGURE 3: READ CYCLE TIMING DIAGRAM

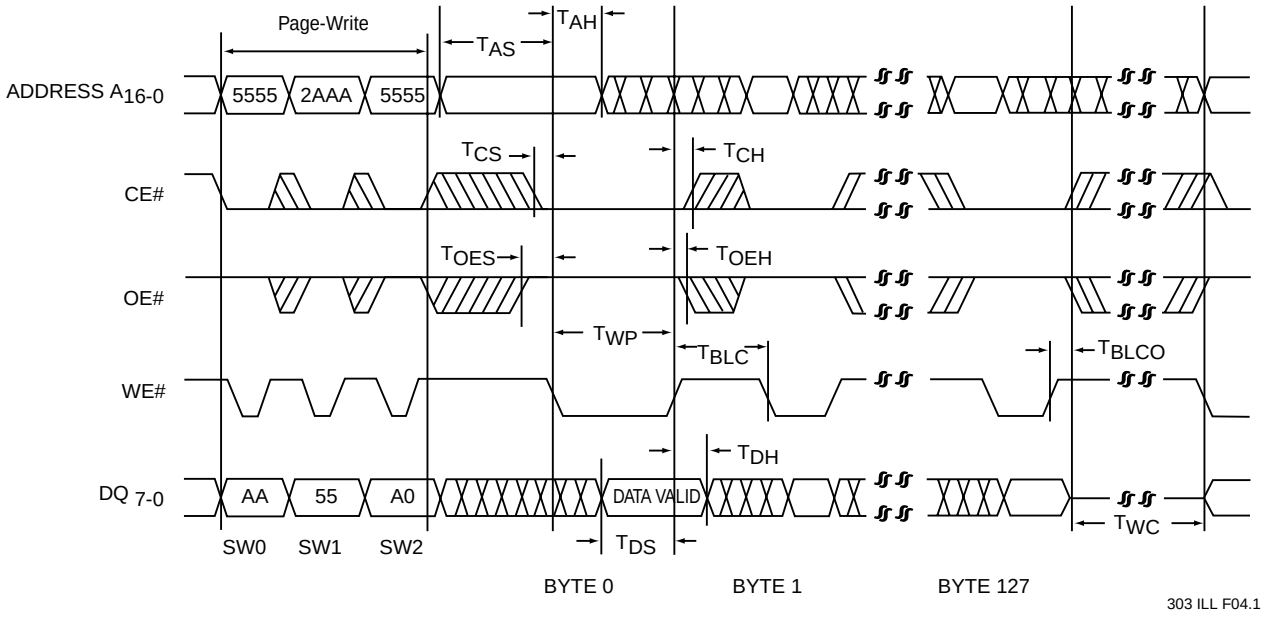


FIGURE 4: WE# CONTROLLED PAGE-WRITE CYCLE TIMING DIAGRAM

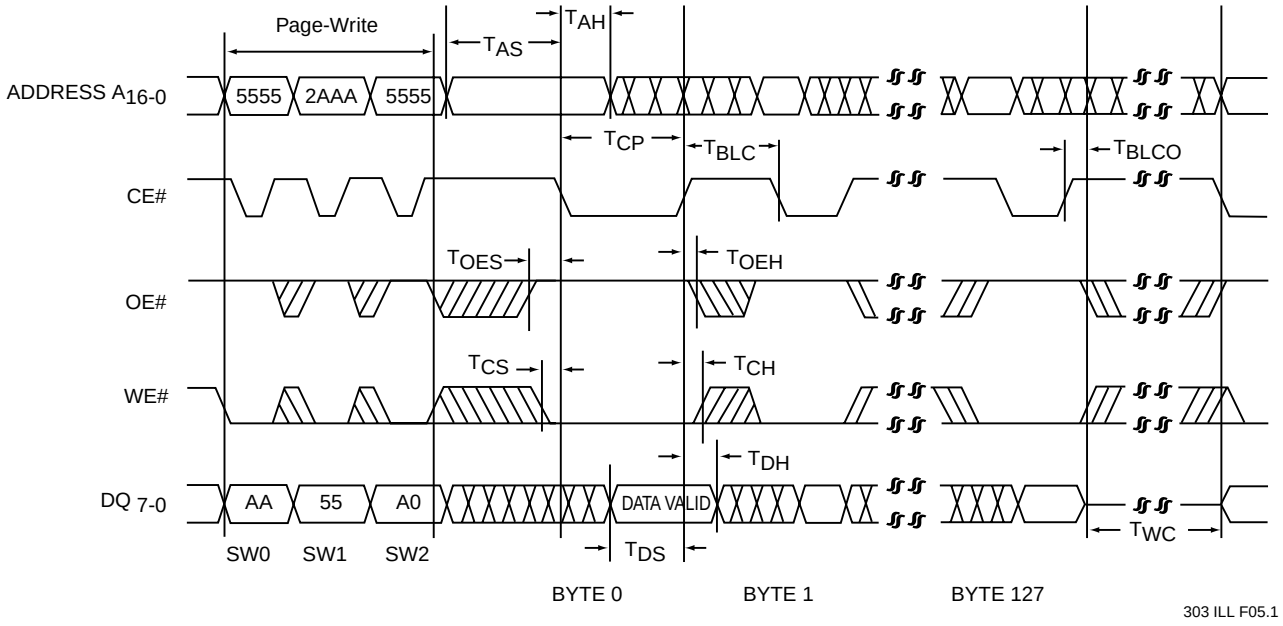


FIGURE 5: CE# CONTROLLED PAGE-WRITE CYCLE TIMING DIAGRAM

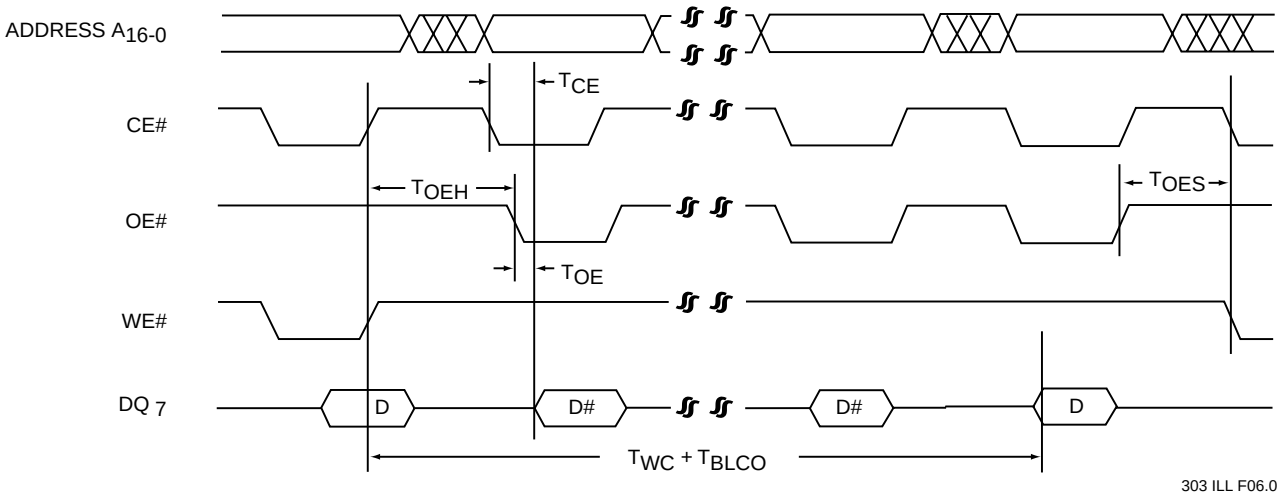


FIGURE 6: DATA# POLLING TIMING DIAGRAM

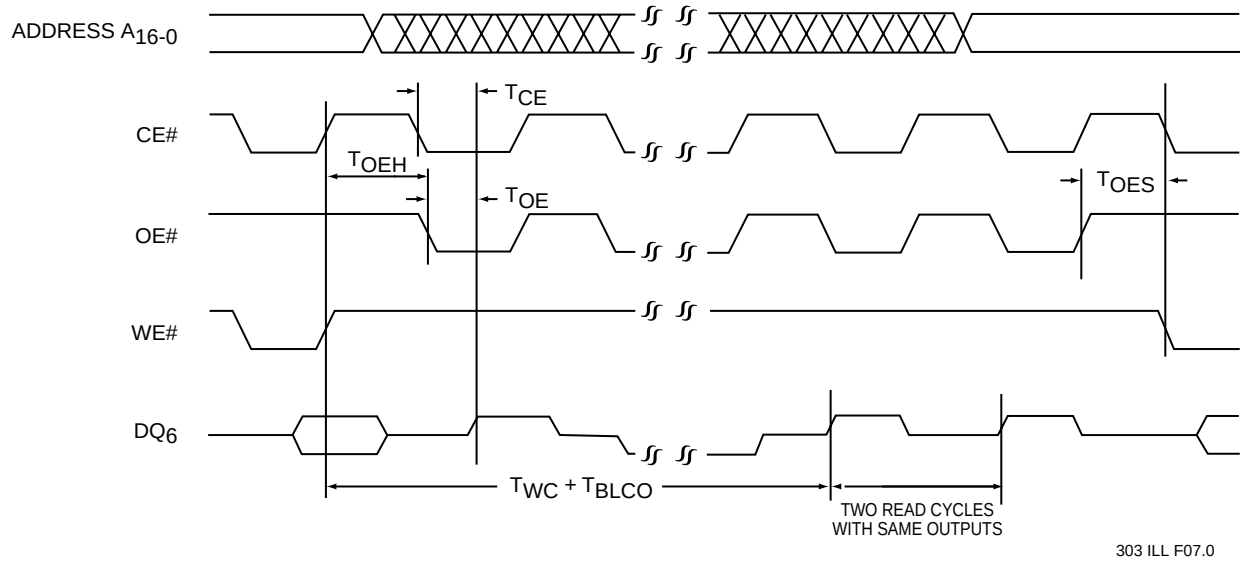


FIGURE 7: TOGGLE BIT TIMING DIAGRAM

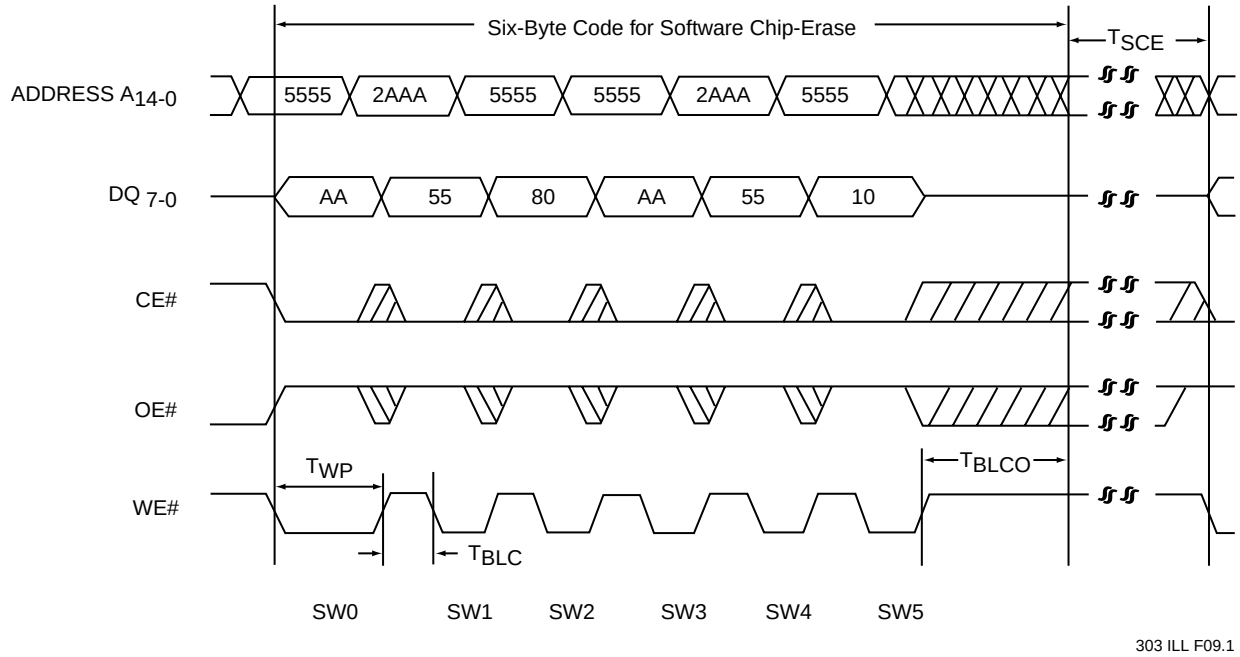


FIGURE 8: SOFTWARE CHIP-ERASE TIMING DIAGRAM

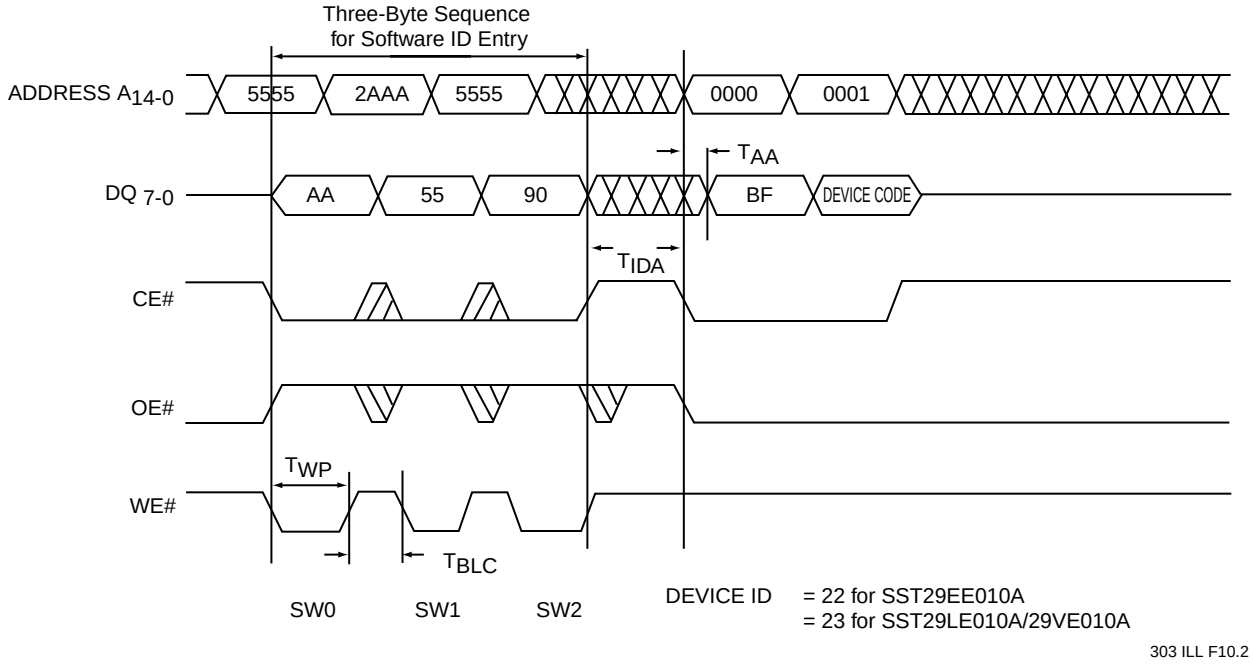


FIGURE 9: SOFTWARE ID ENTRY AND READ

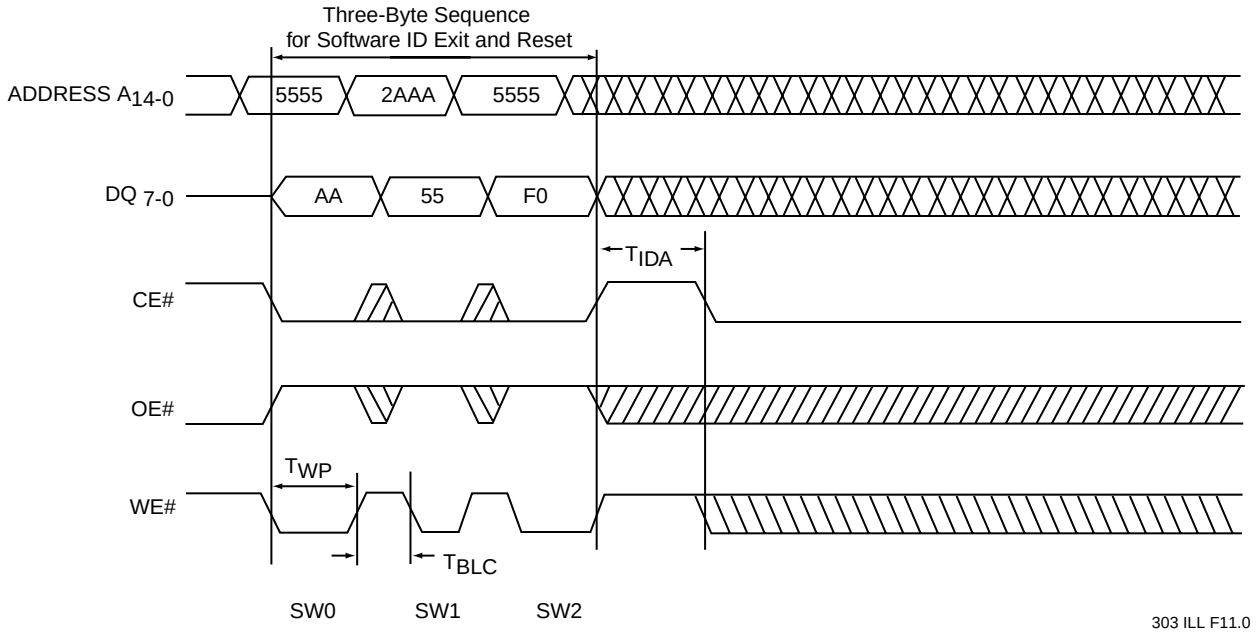
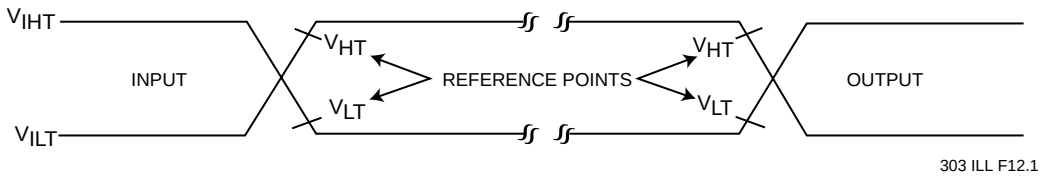


FIGURE 10: SOFTWARE ID EXIT AND RESET



AC test inputs are driven at V_{IHT} (2.4 V) for a logic "1" and V_{ILT} (0.4 V) for a logic "0". Measurement reference points for inputs and outputs are V_{HT} (2.0 V) and V_{LT} (0.8 V). Inputs rise and fall times (10% ↔ 90%) are <10 ns.

Note: V_{HT}–V_{HIGH} Test
V_{LT}–V_{LOW} Test
V_{IHT}–V_{INPUT} HIGH Test
V_{ILT}–V_{INPUT} LOW Test

FIGURE 11: AC INPUT/OUTPUT REFERENCE WAVEFORMS

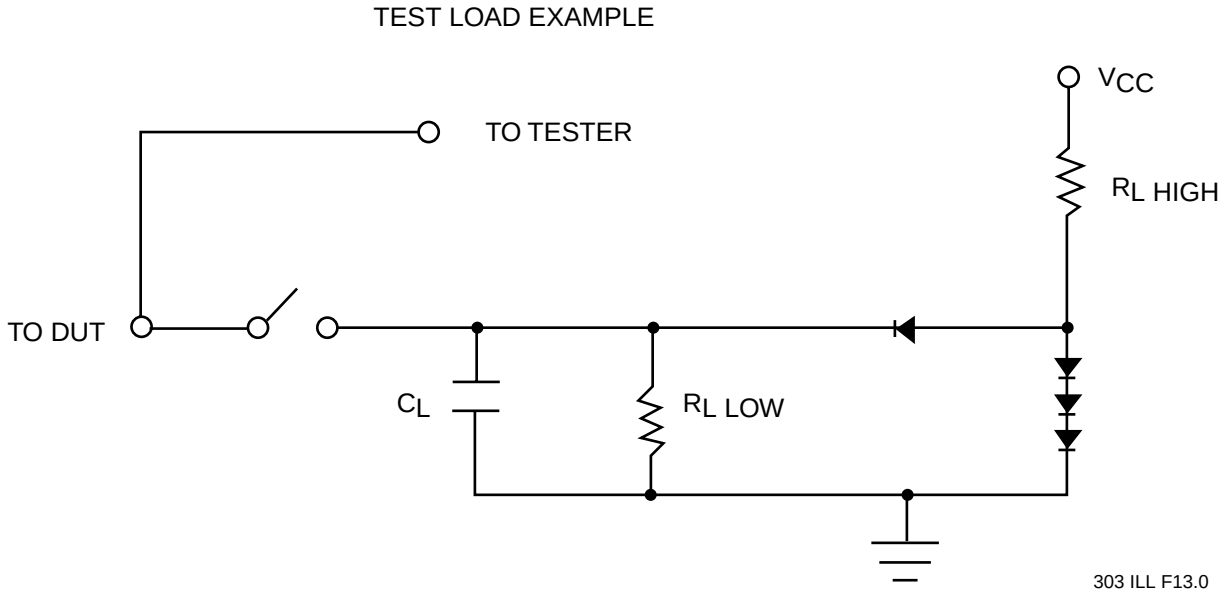


FIGURE 12: A TEST LOAD EXAMPLE

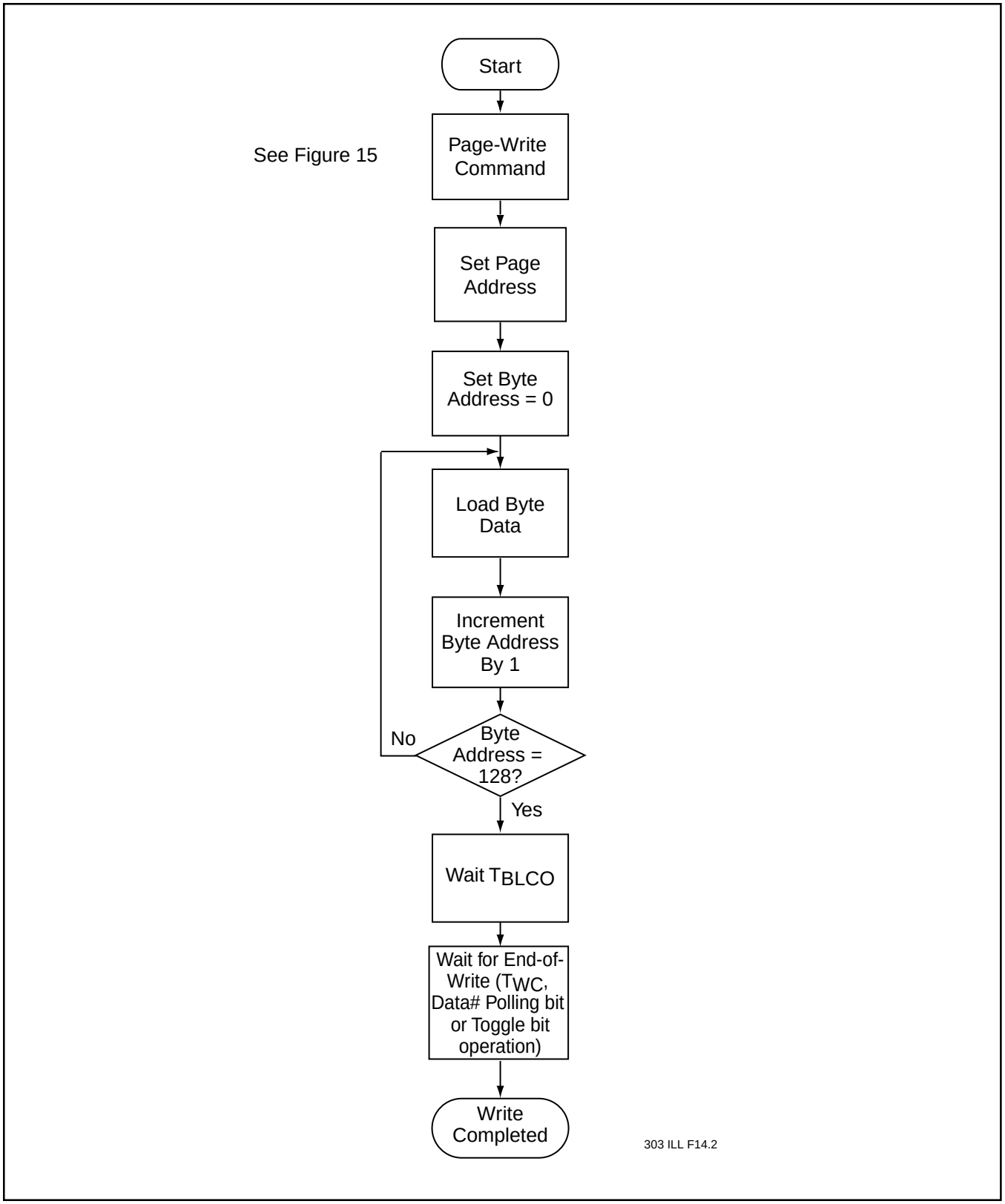


FIGURE 13: WRITE ALGORITHM

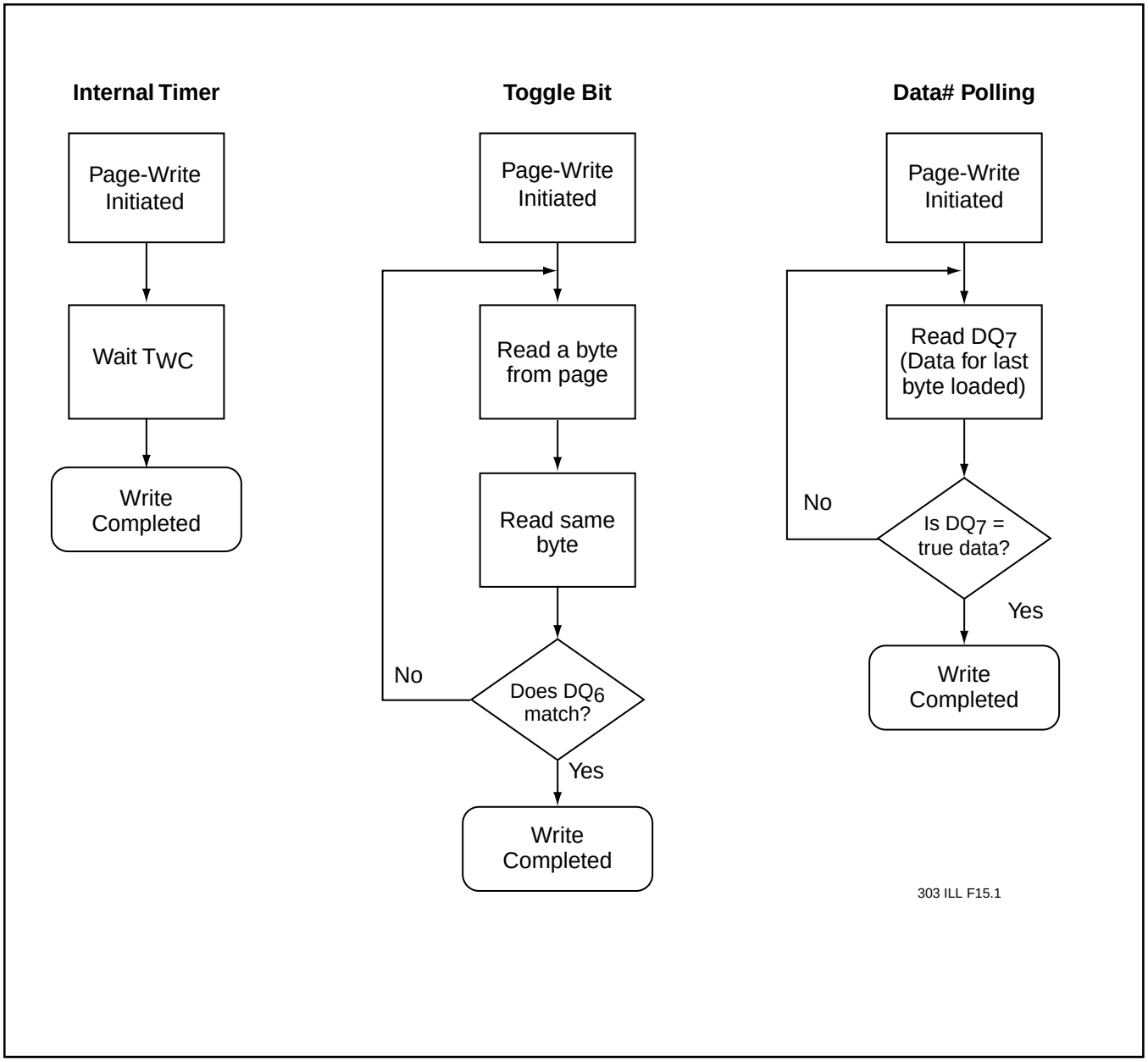


FIGURE 14: WAIT OPTIONS

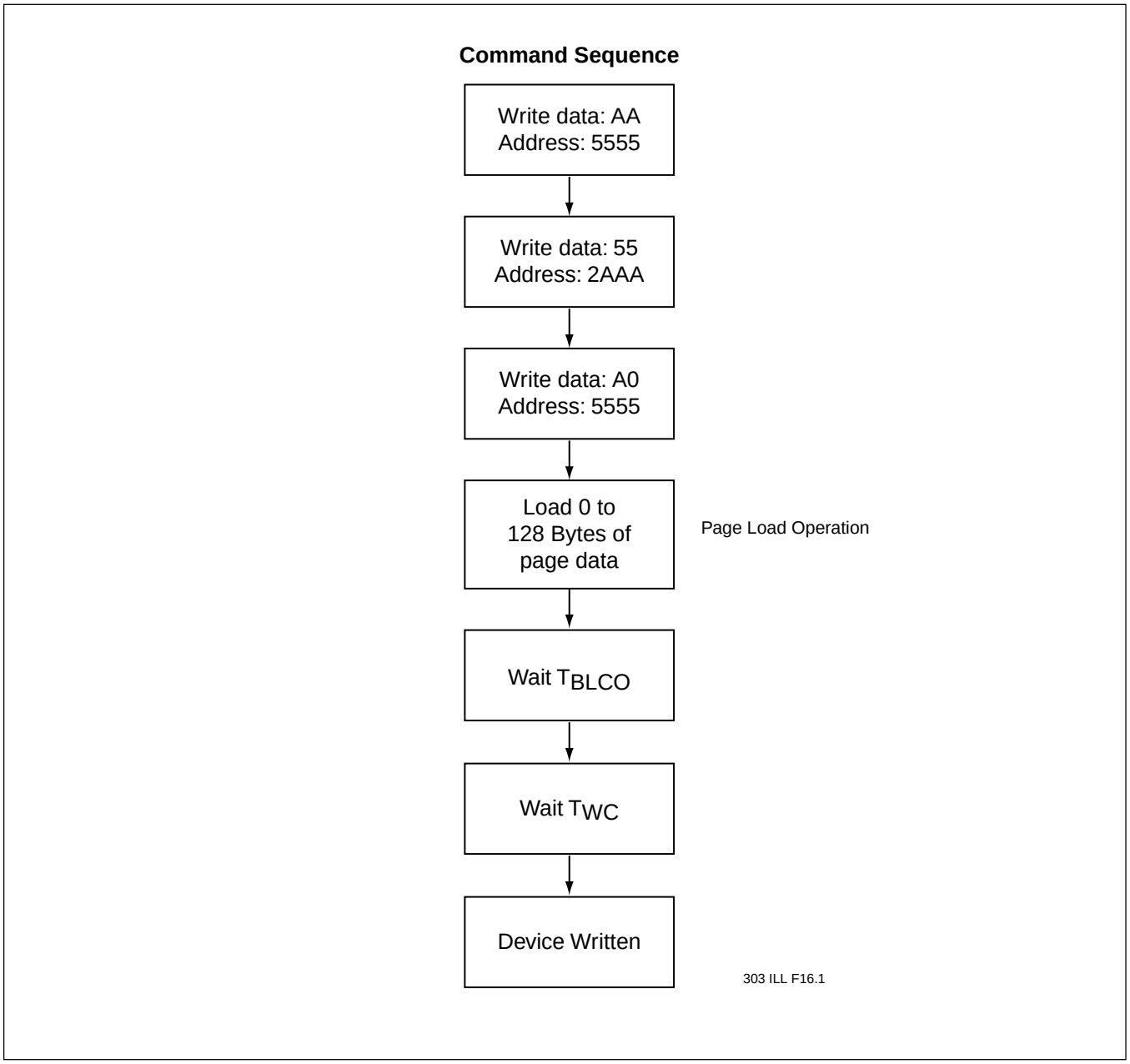


FIGURE 15: PAGE-WRITE FLOWCHART

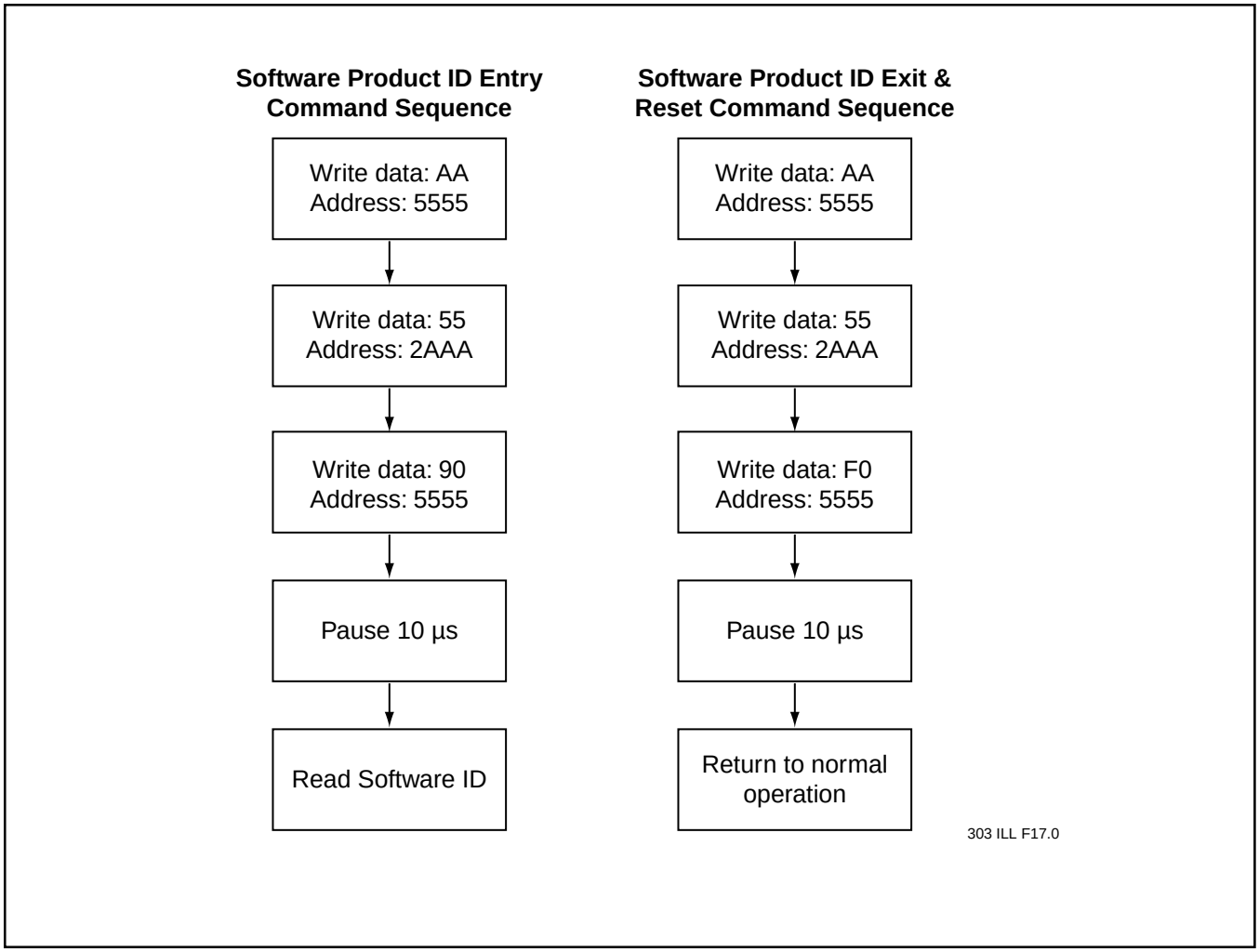


FIGURE 16: SOFTWARE PRODUCT COMMAND FLOWCHARTS

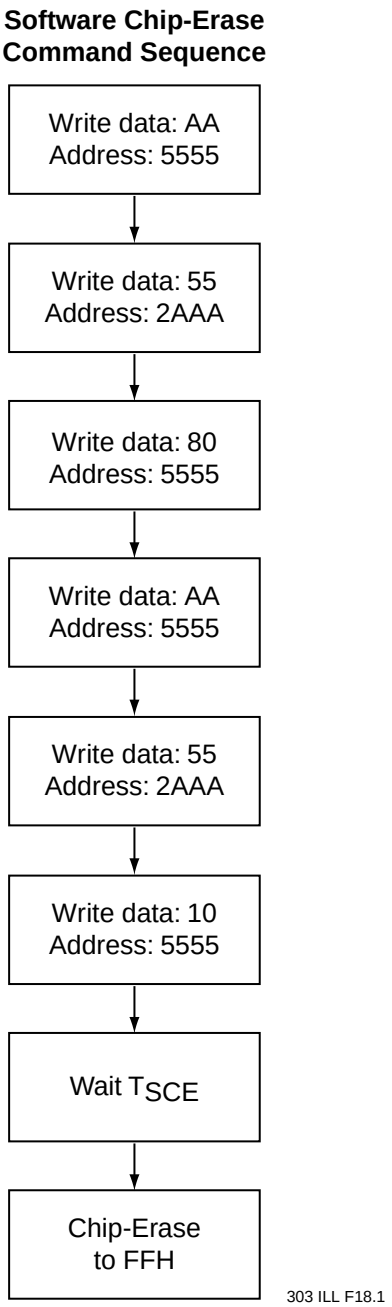
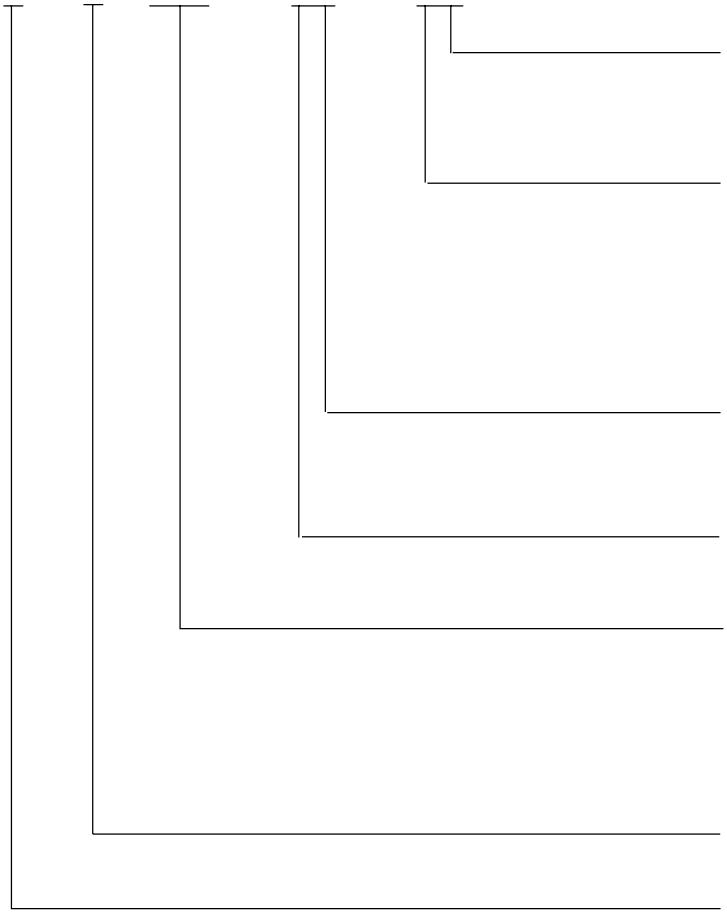


FIGURE 17: SOFTWARE CHIP-ERASE COMMAND CODES

PRODUCT ORDERING INFORMATION

Device **Speed** **Suffix1** **Suffix2**

SST29xE010A - XXX - XX - XX



Package Modifier
- H = 32 leads
- Numeric = Die modifier

Package Type
- P = PDIP
- N = PLCC
- E = TSOP (die up) 8mm x 20mm
- W = TSOP (die up) 8mm x 14mm
- U = Unencapsulated die

Operating Temperature
- C = Commercial = 0° to 70°C
- I = Industrial = -40° to 85°C

Minimum Endurance
- 4 = 10,000 cycles

Read Access Speed
- 250 = 250 ns
- 200 = 200 ns
- 150 = 150 ns
- 120 = 120 ns
- 90 = 90 ns

Version Code

Voltage
- E = 5.0V-only
- L = 3.0 - 3.6V
- V = 2.7 - 3.6V

SST29EE010A Valid combinations

SST29EE010A-90-4C-EH	SST29EE010A-90-4C-NH	SST29EE010A-90-4C-PH
SST29EE010A-120-4C-EH	SST29EE010A-120-4C-NH	SST29EE010A-120-4C-PH
SST29EE010A-90-4C-WH		
SST29EE010A-120-4C-WH		
SST29EE010A-90-4I-EH	SST29EE010A-90-4I-NH	
SST29EE010A-120-4I-EH	SST29EE010A-120-4I-NH	
SST29EE010A-120-4C-U2		

SST29LE010A Valid combinations

SST29LE010A-150-4C-EH	SST29LE010A-150-4C-NH	SST29LE010A-150-4C-WH
SST29LE010A-200-4C-EH	SST29LE010A-200-4C-NH	SST29LE010A-200-4C-WH
SST29LE010A-150-4I-EH	SST29LE010A-150-4I-NH	SST29LE010A-150-4I-WH
SST29LE010A-200-4C-U2		

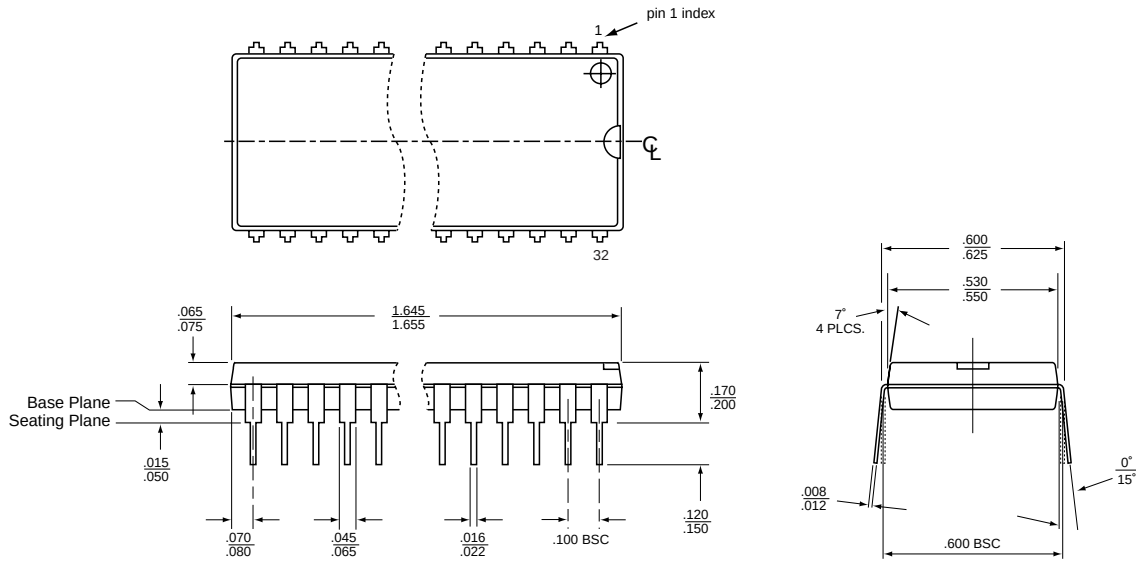
SST29VE010A Valid combinations

SST29VE010A-200-4C-EH	SST29VE010A-200-4C-NH	SST29VE010A-200-4C-WH
SST29VE010A-250-4C-EH	SST29VE010A-250-4C-NH	SST29VE010A-250-4C-WH
SST29VE010A-200-4I-EH	SST29VE010A-200-4I-NH	SST29VE010A-200-4I-WH
SST29VE010A-250-4C-U2		

Example: Valid combinations are those products in mass production or will be in mass production. Consult your SST sales representative to confirm availability of valid combinations and to determine availability of new combinations.

Note: The software Chip-Erase function is not supported by the industrial temperature part.
Please contact SST, if you require this function for an industrial temperature part.

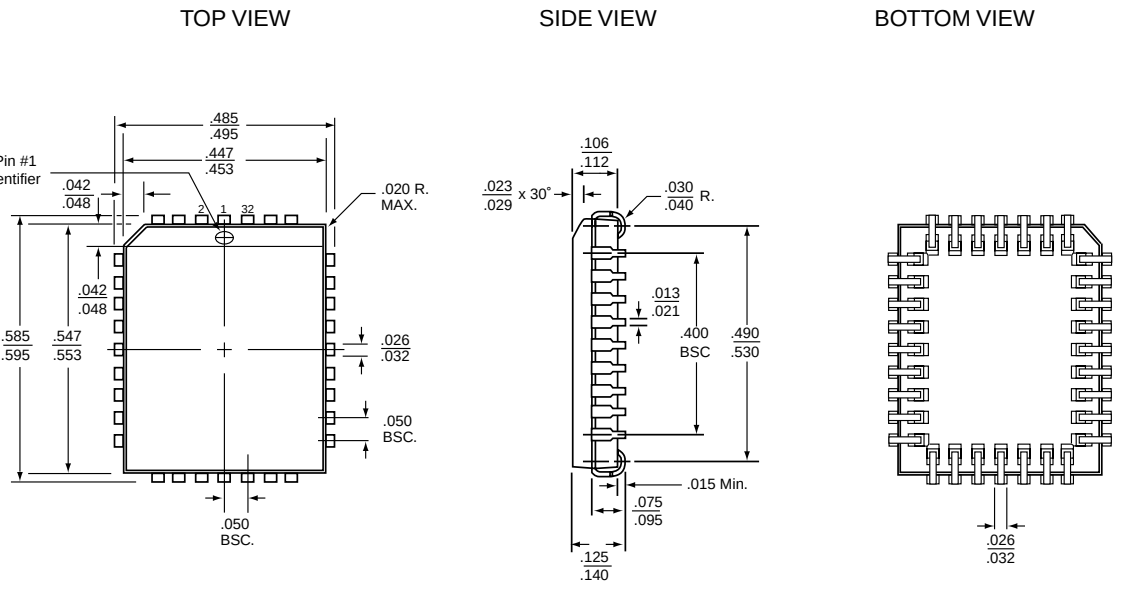
PACKAGING DIAGRAMS



Note: 1. Complies with JEDEC publication 95 MO-015 AP dimensions, although some dimensions may be more stringent.
2. All linear dimensions are in inches (min/max).
3. Dimensions do not include mold flash. Maximum allowable mold flash is .010 inches.

32.pdipPH-ILL.1

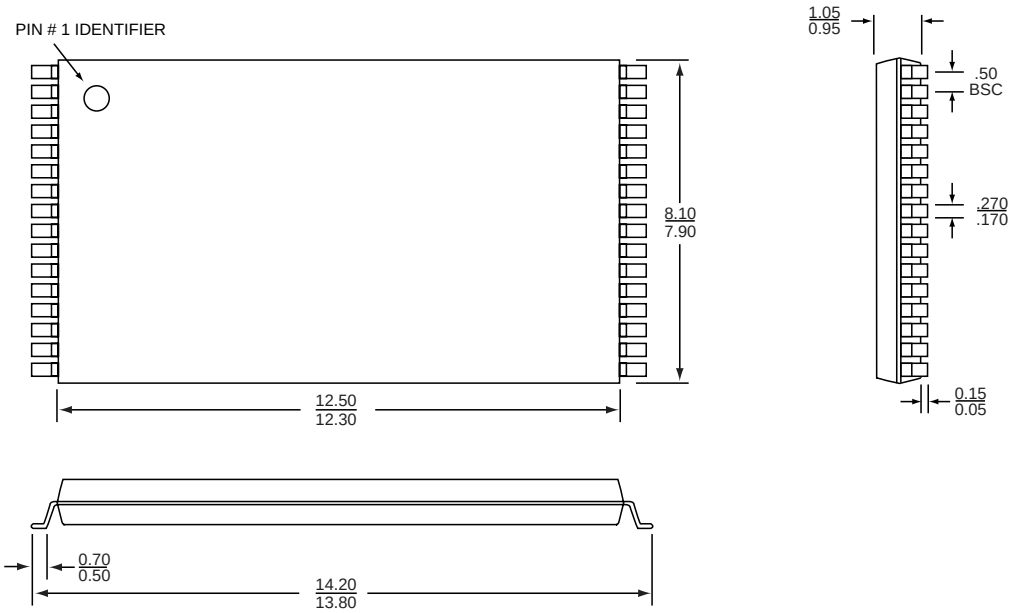
32-LEAD PLASTIC DUAL-IN-LINE PACKAGE (PDIP)
SST PACKAGE CODE: PH



Note: 1. Complies with JEDEC publication 95 MS-016 AE dimensions, although some dimensions may be more stringent.
2. All linear dimensions are in inches (min/max).
3. Dimensions do not include mold flash. Maximum allowable mold flash is .008 inches.

32.PLCC.NH-ILL.1

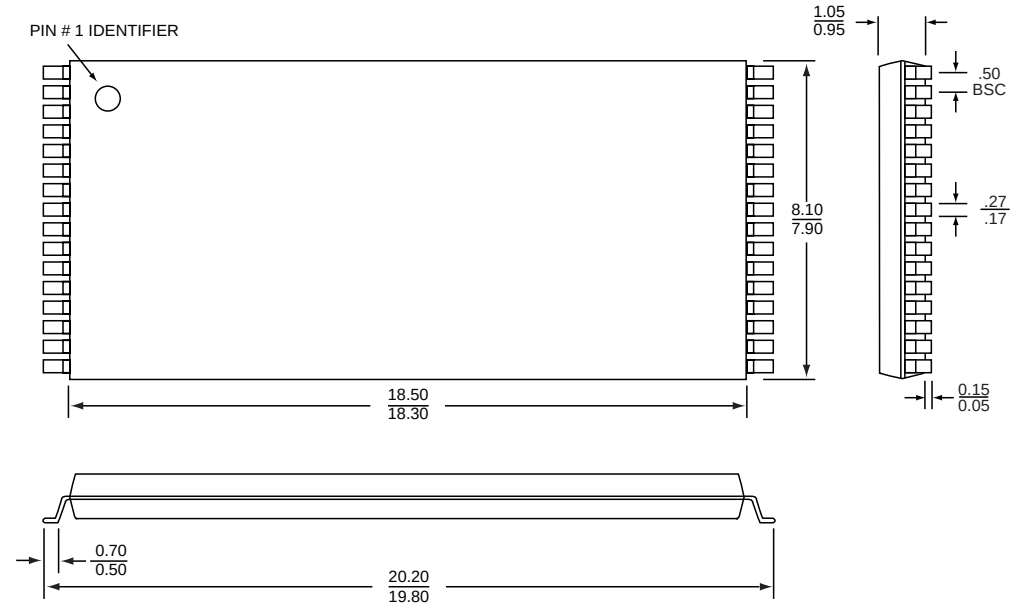
32-LEAD PLASTIC LEAD CHIP CARRIER (PLCC)
SST PACKAGE CODE: NH



Note: 1. Complies with JEDEC publication 95 MO-142 BA dimensions, although some dimensions may be more stringent.
2. All linear dimensions are in millimeters (min/max).
3. Coplanarity: 0.1 (±.05) mm.

32.TSOP-WH-ILL.3

32-LEAD THIN SMALL OUTLINE PACKAGE (TSOP) 8MM X 14MM
SST PACKAGE CODE: WH



Note: 1. Complies with JEDEC publication 95 MO-142 BD dimensions, although some dimensions may be more stringent.
2. All linear dimensions are in millimeters (min/max).
3. Coplanarity: 0.1 (±.05) mm.

32.TSOP-EH-ILL.3

32-LEAD THIN SMALL OUTLINE PACKAGE (TSOP) 8MM X 20MM
SST PACKAGE CODE: EH